Modulation of the morphology, microstructural and magnetic properties on electrodeposited NiFeCu alloys

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Abstract
In this work, the correlations between synthesis, microstructural characteristics and magnetic properties of electrodeposited NiFeCu alloys were investigated using a factorial design procedure. The molar concentration of Ni, Fe and Cu was determined by Inductively Coupled Plasma Optical Emission Spectrometry. Field Emission Gun Scanning Electron Microscopy and Atomic Force Microscopy images ensure that all films present surface homogeneity and similar grain structure. X-ray diffraction data, analyzed using Rietveld refinement, showed that the NiFeCu alloys present faceted cubic structure with preferential orientation in the [111] direction perpendicular to the electrode surface. It is shown that electrochemically prepared NiFeCu, can be produced to have different microstructural characteristics and composition which optimize relevant magnetic features, such as remanent (\(M_r\)) and saturation magnetization (\(M_s\)).

1. Introduction

The magnetic properties of alloys and multilayers have been investigated due to their potential application in different technological devices such as computer reader/writer heads [1], magnetic sensors [2], electromagnetic shielding [3,4], permanent magnets [5] and microelectromechanical system (MEMS) [6,7].

It is known from literature papers that the magnetic properties of electrodeposited alloys can be directly related not only to the composition, but also to microstructural properties, such as crystallite size, grain size, and crystal lattice deformation (strain) [8–15]. Sun et al. [16] have observed an increase in the coercivity and in the saturation magnetization for NiFe alloys associated with the increase of Fe content, leading to an anisotropic magnetic behavior. From a different point of view, Sanaty-zadeh et al. [17] have reported a decrease in the coercivity of NiFe alloys as the grain size decreases.

Different physical techniques, such as Physical Vapor Deposition (PVD), Plasma Spraying (PS) and Sputtering can be employed for film deposition. Nevertheless, wet routes like electroless and electrochemical depositions have been proven to be very efficient to obtain samples with good crystallinity, morphological quality, and high reproducibility. Besides that, electrochemical experimental parameter modulation, such as deposition potential, pH, additives, and temperature, allow the preparation of materials with a variety of morphologies. For example, the addition of saccharin to the plating solution has been used to prepare magnetic alloy with lower coercivity [18,19]. In addition, it improves the brightness of the deposit, tunes the crystal structure, decreases the grain sizes and reduces the residual stress [20]. Among its many advantages, the electrodeposition technique requires simple and inexpensive equipment, leading to a low cost of production compared to other deposition methods which require ultra-high vacuum [21–23].

The application of soft magnetic electrodeposited alloys to electronic devices have grown considerably in recent decades, for example, the use of Ni80Fe20 (Permalloy) and Ni45Fe55 alloys as reader/writer magnetic shield materials due to their high saturation magnetic flux density [24]. Besides, the addition of cooper, a nonmagnetic element, to the NiFe alloys, leads to Giant Magneto-resistance (GMR) effect. In this case, Cu plays an important role as a non-magnetic spacer in the crystal lattice of NiFe alloys and presents low lattice mismatch to the NiFe lattice common one. Specifically, for NiFeCu alloys synthesized using electrochemical methods, there are a small number of published papers [14,25–27]. Considering that electrochemical procedures have been poorly explored on preparing NiFeCu alloys, we present an experimental study on the correlation between the microstructural and morphological changes in the magnetic properties of electrodeposited thick films of NiFeCu alloys.

2. Experimental

2.1. Sample electrodeposition

The deposition bath was composed of 1.0 mol L⁻¹ NiSO₄·7H₂O (Synth), 0.04 mol L⁻¹ FeSO₄ 7H₂O (Sigma-Aldrich), 0.01 mol L⁻¹ 1.0 mol L⁻¹ NiSO₄·7H₂O (Synth), 0.04 mol L⁻¹ FeSO₄ 7H₂O (Sigma-Aldrich), 0.01 mol L⁻¹
CuSO₄·5H₂O (Reagen), 0.4 mol L⁻¹ H₂BO₃ (Merck) and 0.01 mol L⁻¹ saccharin (Synth). All solutions were prepared with water purified by a Millipore Milli-Q system (resistivity >18.2 MΩ cm) and analytical grade reagents. The pH of the solution was measured and it was equal to 3.0. Before each electrochemical synthesis, the electrolyte solution was bubbled with N₂ flux for 10 min. The N₂ flux was kept over the solution during the whole experiment. The NiFeCu alloys were electrodeposited in a three-electrode glass cell at constant temperature using a thermostatic bath (Cole Parmer, model 12104). The electrodeposition of the alloys was performed with electrodes positioned horizontally in stagnant solution. The electrochemical data were collected using an Autolab Model PGSTAT302 (Metrohm Eco Chemie) under potentiostatic conditions. The substrate for the depositions was polycrystalline Pt (A = 10 mm × 10 mm). Pt sheet (A = 2.74 cm²) was used as an auxiliary electrode and Ag/AgCl (KCl sat.) as the reference electrode.

2.2. Factorial design for the alloys synthesis

In the factorial design procedure the influence of all experimental variables are evaluated simultaneously. The largest advantage of this method is the evaluation of cross effects between different variables using the same set of experiments. The effects are evaluated by a matrix calculation which combines all variables at their different levels [28,29]. For the case of a combination of n variables at k different levels, a factorial design consists of kⁿ experiments. In this work 3 variables at 2 different levels were investigated leading to 8 (2³) experiments. The parameters evaluated are deposition potential, deposition time and temperature of the plating bath.

In Table 1 the values of each experimental variable are presented. The samples were prepared and measured in duplicates and the Student’s t-distribution with 8 degrees of freedom and 95% confidence interval was used to calculate the experimental error associated with the individual responses [28,29].

2.3. Characterization of NiFeCu alloys

The factorial design approach (Table 1) considered eight (8) samples, as well as, their duplicates. Their microstructural properties were investigated by the X-ray diffraction (XRD) using a SHIMADZU diffractometer, model XRD-6000, with CuKα radiation (λ = 1.5406 Å). A 0–20 scan from 30° until 110° with a scan rate of 0.2°/min and step scan of 0.02° were performed at room temperature. The crystalline phases were identified using the Inorganic Crystal Structure Database (ICSD).

XDR data was analyzed by Rietveld refinement [30] using GSAS-EXPEGUI software [31]. The peak profile was fitted by a Pseudo-Voigt function of Thompson-Cox-Hasting modified by Young and Desai (pv-TCHZ) [32]. The background was corrected by an eighth-degree shifted Chebyshev polynomial function and the preferential orientation was estimated using spherical harmonics of eighth order, following a model suggested by Jarvinen [33]. In Rietveld method, the process of convergence is accompanied by χ², RWP and RF² factors and a good data fit gives precise information on crystallite size, strain, preferential orientation and crystalline phases.

The film morphologies were investigated by Field Emission Gun Scanning Electron Microscopy (FEG-SEM) using a ZEISS microscope (model 105 DSM940A), with 10 keV of accelerating voltage. The Atomic Force Microscopy (AFM) mapping was performed using an Agilent series 5500 (Agilent Technologies) operating in contact mode at room temperature. A scanner of 100 μm and silicon probes (NanoSensors) with a spring constant of 10–130 N/m was used. AFM images were recorded scanning an area of 5 μm × 5 μm at a rate of 1.0 line/s. The roughness mean square (RMS) was derived from AFM micrographs using Gwyddion software [34].

The elementary chemical composition of the alloy was determined by Inductively Coupled Plasma Optical Emission Spectrometry (ICP-OES) Perkin Elmer model Optima 8300.

The magnetization was measured as a function of the applied magnetic field (M × H) performed up to 70 kOe at room temperature, using a SQUID-VSM magnetometer (MPMS®3 – QDUSA).

3. Results and discussion

A set of NiFeCu alloy films were produced using experimental conditions as described in Table 1. The electrodeposition processes were performed measuring the current-time transients. Fig. 1 shows a typical current-time transient during the electrodeposition process. The current rapidly reaches a steady state in a few seconds after the process of nucleation and the growth starts, ensuring that the metal ions are being uniformly deposited in the sample [35].

The same behavior was observed for all electrodeposition conditions described in Table 1.

The compositions of Ni and Fe in the alloys obtained under different experimental conditions were evaluated using ICP-OES technique and are presented in Fig. 2a and c and Table S1–1 of the Supplementary Information. In this representation, the vertexes of the cube represent the element % composition and the axes indicate the preparation variable (applied potential, deposition time, and temperature).

The effects of the electrodeposition variables are presented by Pareto histograms. Pareto histograms are useful [36] to identify the effect of the

<table>
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<tr>
<th>Table 1</th>
<th>Experimental parameters and levels considered in the factorial design for the electrodeposition procedure.</th>
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<tr>
<td>Variables</td>
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<td>Edep (V)</td>
<td>(+)</td>
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<td>(+)</td>
<td>-1.10</td>
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<td>Deposition time ( min)</td>
<td>15</td>
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<td>(C) Temperature (°C)</td>
<td>40</td>
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<td>25</td>
<td>E4</td>
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<td>35</td>
<td>E5</td>
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<td>45</td>
<td>E6</td>
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Fig. 1. Potentiostatic deposition of Experiment E3, NiFeCu film in 1 M NiSO₄ + 0.04 M FeSO₄ + 0.01 M CuSO₄ + 0.4 M H₂BO₃ + 0.01 M saccharin solution, Edep = -1.03 V, t = 40 min, T = 25 °C.
variables on the responses. In Fig. 2b and d, the standardized effects are presented in a decreasing order of significance. An effect is considered statistically significant, whenever its value is equal or larger than the t-test critical values multiplied by the standard deviation of the effects at a 95% significance level (represented by the dotted vertical line in the chart in Fig. 2b and d with eight degrees of freedom [38].

As shown in Fig. 2b and d, the temperature and the deposition potential are the parameters with the largest effect on the composition of the alloys. The standard reduction potential of Fe\(^{2+}\) (\(\phi^{0}_{Fe^{2+}/Fe} = -0.440\) V) is 0.183 V more negative than Ni\(^{2+}\) (\(\phi^{0}_{Ni^{2+}/Ni} = -0.257\) V) and 0.780 V more negative than Cu\(^{2+}\) (\(\phi^{0}_{Cu^{2+}/Cu} = +0.340\) V). Considering these redox potentials, it is expected that copper deposits first followed by deposition of Ni and Fe, respectively. As a consequence of the higher Ni\(^{2+}\) concentration in the electrodeposition solution the major component of the alloys is Ni (Fig. 2a) as expected. In addition, under all the experimental conditions, an increase of the Ni content reveals a competition between the kinetic reduction of nickel, iron, copper and hydrogen [39]. In our case, the displacement of the deposition potential towards more negative values and an increase in the temperature of the plating bath produce an increase of Ni concentration and a decrease Fe concentration on the alloys. This is an expected effect considering that an increase in the current density (which is a consequence of the applied potential to be more negative) results in an increase of the noble metal content in the coating [39–41].

In Fig. 3 we present surface morphologies obtained by FEG-SEM and AFM techniques of the prepared samples. FEG-SEM micrographs indicate the formation of films with similar grain structure and surface homogeneity [27] and AFM data show an increase in the grain size. This increase in the grain size could be related to the decrease in iron content in the alloy, as proposed by Sanaty-Sadeh et al. [42].

XRD profile in Fig. 4 reveals that the samples present a typical pattern of a bulk NiFeCu alloy with face-centred cubic (FCC) structure and Fm3m spatial group (ICSD 108378). The mean crystallite size, strain, lattice parameters and preferential orientation were calculated using the Rietveld refinement. This method revealed that all films of NiFeCu exhibit preferential crystallographic orientation in the [111] direction perpendicular to the film. The goodness of the data fit could be confirmed by \(\chi^2\), \(R_{wp}\) and \(R_F^2\) which are presented in Table SI-3 (Supplementary Information). All the results calculated by this method is shown in Table SI-4 (Supplementary Information).

Literature papers have reported that there is a strong correlation between changes in the chemical composition, crystallite sizes, and strain on the magnetic properties observed in many materials [8–10,13,43]. The influence of electrodeposition parameters on the magnetic properties of NiFeCu alloys was evaluated determining the magnetization as a function of the applied magnetic field (M × H) at 300 K (Fig. 5). The values of the saturation magnetization (\(M_s\)) and the remanent magnetization (\(M_r\)) are shown using the geometric representation for all experimental conditions in Fig. 5b and d.
Fig. 5a shows an increasing $M_r$ related to the NiFeCu alloy composition and exhibiting a maximum value of 83.4 emu g$^{-1}$ at 300 K. Besides, NiFeCu films display a small hysteretic behavior and exhibit a low coercivity ($H_C$) in the range of 29 Oe to 33 Oe. These values are found to be within the limits of soft ($H_C < 12.5$ Oe) and hard ($H_C > 125$ Oe) magnetic material, being named as semi-hard ferromagnets.

In Fig. 5b, the geometric representation of $M_r$ reveals that NiFeCu alloys have magnetic properties dependent on the composition and/or microstructural characteristics. The Pareto diagram (Fig. 5c and d) present the calculated standardized effect represented at Table SI-2 (Supplementary Information). The cross-effects of two-factors are also statistically significant for $M_r$ and $M_s$. This means that to optimize the properties of the materials it is not enough to consider the optimization of just one variable, but it is mandatory to consider the cross effects that modulates the results [29]. Furthermore, the Pareto charts show that potential and temperature, are the most relevant variables that contributed significantly to increase $M_r$ and $M_s$. This means a decrease of $-16.2 \pm 3.6$ emu g$^{-1}$ and $-7.2 \pm 2.3$ emu g$^{-1}$ for $M_r$ and $M_s$, respectively, for potentials of $-1.03$ V to $-1.10$ V. Besides, when the temperature of deposition is increased, from 25 °C to 45 °C, there is a decrease of $-19.6 \pm 3.6$ emu g$^{-1}$ for $M_r$ and of $-3.2 \pm 2.3$ emu g$^{-1}$, for $M_s$. As far as the time variable is concerned it was found that $M_r$ decreases as deposition time increases, while, $H_C$ increases slightly (Table SI-5 — Supplementary Information). The film thickness was found proportional to the deposition time, therefore, one can associate the time of deposition with the literature data correlating the thickness of the films with $M_r$ and $H_C$ [44]. These results are consistent with the assumption that thicker films are likely to have a larger number of domains, resulting on an effective smaller remanence due to the domain structure [45].

These results suggest that the magnetic properties are associated with changes in the microstructure and/or composition of the alloys.
In Fig. 6 the dependence of MS on the Ni and Fe content is presented. Using the red line as an eye guide, it is observed that the increase of MS is followed by an increase of Fe and a decrease of Ni contents in the alloy. This is an expected behavior while the moment/atom for elemental Fe, $\mu_B = 2.2$ Bohr magnetron, is greater than that for Ni ($\mu_B = 0.6$) [46]. Besides, it is important to stress that MS is an extensive characteristic of a material depending on composition, grain size and lattice strain. Therefore, it is necessary to consider the microstructural characteristics to evaluate magnetic properties.

Internal strains can influence the physical properties of almost all magnetic materials [47]. One of these effects is known as magnetostriction. A typical magnetostriction effect is caused during the deposition process and this effect is revealed in $M \times H$ curves [46]. For NiFe alloys this effect was already observed [48] by Butta et al. In our case, the calculated strain, calculated from XRD data Rietveld refinement, ranged from 2.01% to 3.05% (Table SI-4 — Supplementary Information). In Fig. 7 the square of the magnetization normalized by the saturation magnetization, $(M/MS)^2$, is presented as a function of the applied magnetic field, for different NiFeCu alloys at 300 K. As can be observed in Fig. 7, the curves quickly increase in the region of low fields and then slowly achieve the saturation. The difference between the curves in the low field region arises due to domain walls movement.
[49] and to different strains generated during the electrodeposition process, which give origin to the magnetostriction effect. The magnetostriction effect is directly proportional to \((\sqrt{M/MS})^2\) [47]. The arrow in Fig. 7 shows a decrease in \((\sqrt{M/MS})^2\) associated with the decreasing lattice strain.

Several published results describe that the remanent magnetization is strongly dependent on the crystallite size \((D)\) [50–55]. In Fig. 8a \(M_R \times D\) data is presented, showing an increase in the remanent magnetization for \(D\) such as \(5.4 \leq D \leq 6.1\) at 25 °C and \(6.6 \leq D \leq 7.7\) at 45 °C. The same pattern is observed when the remanent magnetization is plotted as a function of the Fe content as shown by a linear dependence between \(M_R\) on %Fe (Fig. 8b). The remanent magnetization as a function of %Ni follows the expected linear decrease due to the decreasing effective moment/atom.

In conclusion, the employed technique was effective for obtaining NiFeCu films with the desired microstructural characteristics and composition to optimize magnetic relevant features, such as remanent \((M_R)\) and saturation magnetization \((M_S)\).

4. Conclusions

In this work, we have shown that using standard electrochemical variables it is possible to control the magnetic properties aiming at different applications. The modification of electrodeposition parameters using factorial design allowed us to obtain significant changes in the magnetic properties of the alloys and to quantify the effects of each variable, as well as, the existence of cross effect as clearly seen in Pareto diagrams. The potential of deposition and temperature of the plating bath causes consistent changes of composition, morphology, microstructure and magnetic properties of the alloys.

All electrodeposited NiFeCu alloys exhibit face-centred cubic (FCC) crystalline structure with preferential orientation in the \([111]\) direction. Morphology analysis indicates that NiFeCu alloy films have similar grainy structure and surface homogeneity. AFM data shows that increasing the temperature of the plating bath increases grain size.

The study of the correlation between the magnetic behavior and the microstructural characteristics show that an increase in magnetostriction effect is associated with an increase in the lattice strain calculated by XRD Rietveld refinement. In addition, the magnetic behavior of the films shows that the remanent \((M_R)\) and saturation magnetization \((M_S)\) depends strongly on the Ni and Fe contents, on the lattice stress and on the crystallite size.

The geometric representation and Pareto chart summarize the general conclusion that the external variables, temperature, potential and deposition time, can be used to prepare NiFeCu alloys controlling standard electrochemical variables.

It is shown that electrochemically prepared NiFeCu films, can be produced to have different microstructural characteristics and composition to optimize magnetic relevant features, such as remanent \((M_R)\) and saturation magnetization \((M_S)\).

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Appendix A. Supplementary data

Supplementary data to this article can be found online at http://dx.doi.org/10.1016/j.surfcoat.2016.12.087.
References


Fig. 8. Dependence of remanent magnetization (M_r) of NiFeCu alloy: a) crystallite size and b) % Fe in the deposit. The red line is a guideline.


